

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is set forth below. The ensuing listing of the claims replaces all prior claims listings.

1-22. (Withdrawn)

23. (Currently Twice Amended) A method for assembling semiconductor devices, comprising:
providing a first semiconductor device;
placing discrete conductive elements over portions of said first semiconductor device; and
positioning a second semiconductor device at least partially over said first semiconductor device,
and a back side of said second semiconductor device contacting at least some of said
discrete conductive elements ~~with a back side of said second semiconductor device with~~
and being stably supported thereby, said back side and said at least some of said discrete
conductive elements being electrically isolated from each other.

24. (Original) The method of claim 23, wherein said positioning said second semiconductor device comprises positioning said second semiconductor device on said at least some of said discrete conductive elements with said back side and said discrete conductive elements in mutual electrical isolation.

25. (Original) The method of claim 24, further comprising:
providing a dielectric coating on at least portions of said discrete conductive elements.

26. (Previously Amended) The method of claim 25, wherein said providing comprises forming at least one of a dielectric oxide and a dielectric polymer coating on said at least portions of said discrete conductive elements.

27. (Previously Amended) The method of claim 24, wherein said positioning comprises positioning a dielectric layer on at least portions of said back side thereof.

28. (Canceled)

29. (Original) The method of claim 23, further comprising:
applying a quantity of adhesive material to at least an active surface of said first semiconductor device.

BI 30. (Original) The method of claim 29, further comprising:
drawing said second semiconductor device toward said first semiconductor device.

31. (Original) The method of claim 30, wherein said drawing is effected by at least one of capillary action of said adhesive material, curing of said adhesive material, application of heat to said adhesive material, and vibration of said adhesive material.

32. (Original) The method of claim 29, wherein said applying includes applying said quantity of adhesive material to said back side of said second semiconductor device.

33. (Original) The method of claim 29, wherein said applying is effected after said positioning said second semiconductor device.

34. (Original) The method of claim 33, further comprising:
drawing said second semiconductor device toward said first semiconductor device.

35. (Original) The method of claim 34, wherein said drawing is effected during curing of said adhesive material.

36-39. (Withdrawn)

40. (Original) The method of claim 23, further comprising:
securing said first semiconductor device and a substrate to one another.

41. (Previously Amended) The method of claim 40, wherein said placing discrete conductive elements comprises securing said discrete conductive elements to contact areas of said substrate and bond pads of said first semiconductor device.

42. (Original) The method of claim 41, wherein said securing comprises electrically connecting bond pads of said second semiconductor device to corresponding contact areas of said substrate.

BI 43. (Original) The method of claim 42, further comprising:
encapsulating at least a portion of at least one of said substrate, said first semiconductor device, and said second semiconductor device.

44. (Previously Amended) The method of claim 42, further comprising:
forming external conductive elements on said substrate in electrical communication with said corresponding contact areas.

45. (Currently Twice Amended) A method for assembling semiconductor devices in a stacked arrangement with the stacked arrangement having a height substantially equal to combined thicknesses of each of the semiconductor devices and distances discrete conductive elements associated therewith protrude above said each of the semiconductor devices, comprising:
providing a first semiconductor device with discrete conductive elements protruding from an active surface thereof; and

positioning a second semiconductor device at least partially over said first semiconductor device and on at least some discrete conductive elements of said discrete conductive elements such that said second semiconductor device is stably supported by said at least some discrete conductive elements and said back side and said at least some of said discrete conductive elements are electrically isolated from each other.

46. (Original) The method of claim 45, wherein said positioning comprises positioning said second semiconductor device on said at least some of said discrete conductive elements with a back side of said second semiconductor device electrically isolated from said discrete conductive elements.

47. (Original) The method of claim 46, further comprising:
providing a dielectric coating on at least portions of said at least some of said discrete conductive elements.

48. (Previously Amended) The method of claim 46, wherein said positioning comprises positioning a second semiconductor device that includes a dielectric coating on at least portions of said back side thereof.

49. (Original) The method of claim 45, further comprising:
applying a quantity of adhesive material at least to said active surface of said first semiconductor device.

50. (Original) The method of claim 49, further comprising:
drawing said second semiconductor device toward said first semiconductor device.

✓ 51. (Original) The method of claim 50, wherein said drawing is effected by at least one of capillary action of said adhesive material, curing of said adhesive material, application of heat to said adhesive material, and vibration of said adhesive material.

52. (Withdrawn)

53. (Original) The method of claim 49, wherein said applying is effected after said positioning.

54. (Original) The method of claim 53, further comprising:
drawing said second semiconductor device toward said first semiconductor device.

55. (Original) The method of claim 54, wherein said drawing is effected during curing of said adhesive material.

56. (Original) The method of claim 49, further comprising:
biasing at least one of said first and second semiconductor devices toward the other of said first and second semiconductor devices.

57. (Original) The method of claim 56, further comprising:
controlling said biasing.

58. (Original) The method of claim 57, wherein said controlling said biasing comprises controlling biasing force to a level insufficient to deform, kink, bend, or collapse said discrete conductive elements.

59. (Original) The method of claim 45, further comprising:
positioning said first semiconductor device relative to a substrate.

60. (Original) The method of claim 59, further comprising:
connecting said discrete conductive elements to corresponding contact areas of said substrate.

61. (Original) The method of claim 59, further comprising:
establishing electrical communication between bond pads of said second semiconductor device
and corresponding contact areas of said substrate.

62. (Original) The method of claim 61, wherein said establishing communication
comprises:
placing additional discrete conductive elements between each of said bond pads and a
corresponding contact area of said corresponding contact areas.

B1 63. (Original) The method of claim 46, further comprising:
providing at least one external connective element in communication with at least one bond pad
of each of said first and second semiconductor devices.

64. (Original) The method of claim 63, further comprising:
encapsulating at least portions of said first and second semiconductor devices.

65-69. (Withdrawn)
